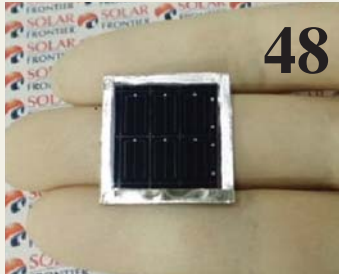




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ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3447-4666. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circmnl@pltdsl.net. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

Taiwan: International Dempa Trade Co., Ltd., 7F-1, No. 36, Nanking W. Rd., Taipei, Taiwan, Tel: +886-2-2558-1817 Fax: +886-2-2555-6428
Korea: Dempa Publications, Seoul Office, Masters Tower, Room 1404, 553 Dohwa-dong, Mapo-ku, Seoul, Korea, 121-040, Tel: +82-2-714-2983 Fax: +82-2-714-2984
Philippines: Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tetsuo Hirayama
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